

SOT1052-1

plastic thermal enhanced extremely thin small outline
package; no leads; 8 terminals; body 2 x 3 x 0.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HXSON8
Package type industry code	HXSON8
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-229
Mounting method type	S (surface mount)
Issue date	11-3-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	[tbd]	-	0.5	0.5	mm
A ₂	package height	[tbd]	-	0.5	[tbd]	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	8	-	

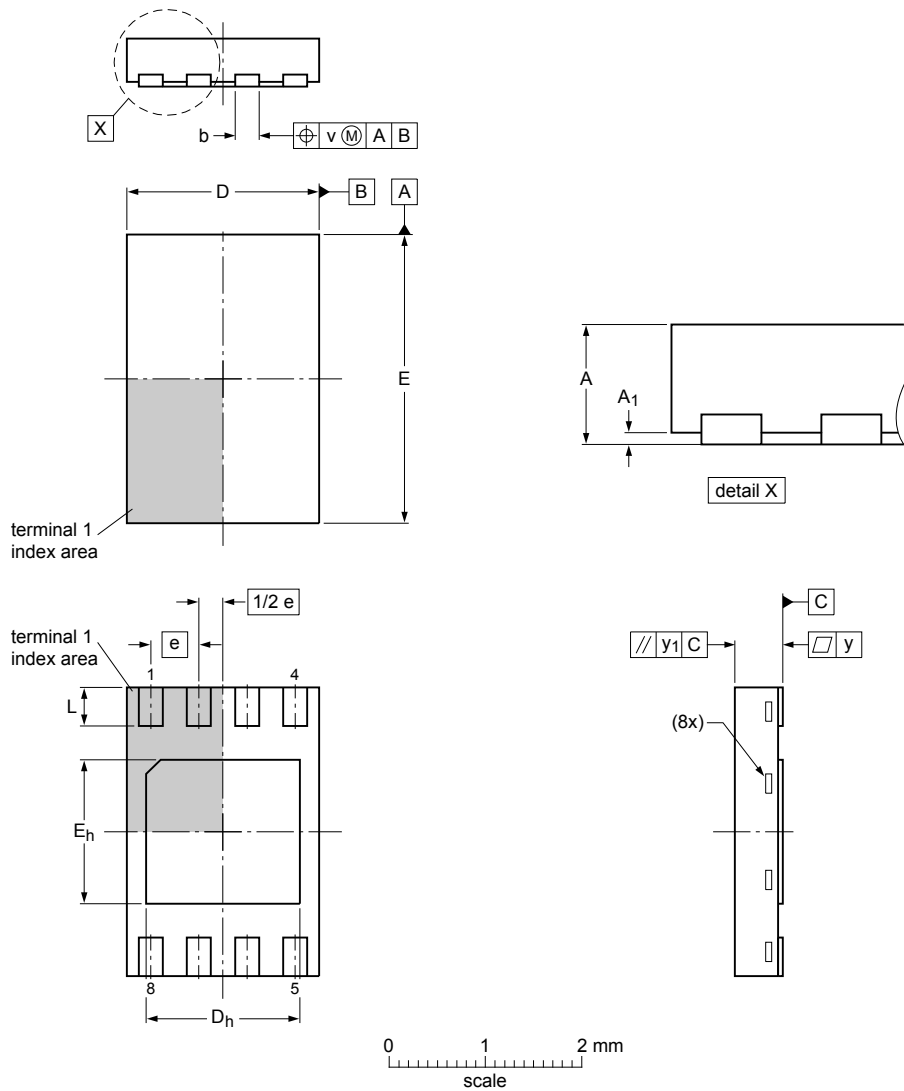


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2. Package outline

HXSON8: plastic thermal enhanced extremely thin small outline package; no leads; 8 terminals; body 2 x 3 x 0.5 mm

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Dimensions

Unit ⁽¹⁾	A ⁽¹⁾	A ₁	b	D	D _h	E	E _h	e	L	v	y	y ₁
max	0.5	0.04	0.3	2.1	1.6	3.1	1.6	0.45				
mm nom				2.0		3.0		0.5		0.1	0.05	0.05
min			0.2	1.9	1.4	2.9	1.4	0.35				

Note

1. Dimension A is including plating thickness. The package footprint is compatible with JEDEC MO229

sot1052-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1052-1		MO-229			-08-01-11- 11-06-27

Fig. 1. Package outline HXSON8 (SOT1052-1)

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3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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